

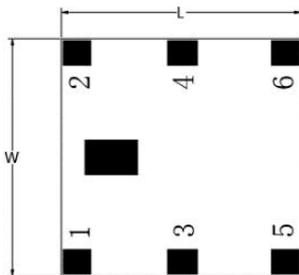
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

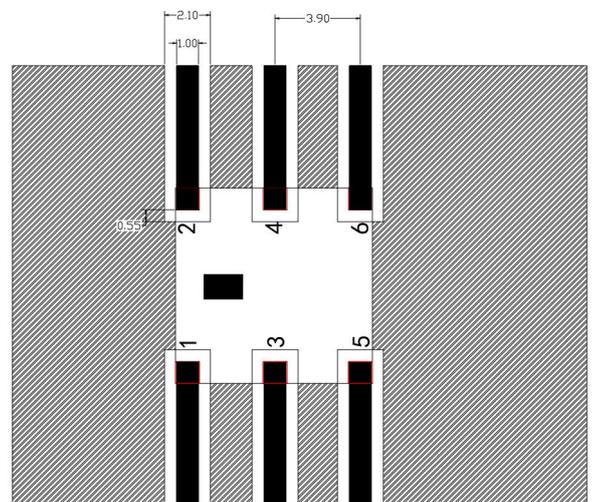
NO.	Specification			
		LPF1	LPF2	LPF3
1	Frequency range (MHz)	225~330	330~480	480~678
2	Insertion Loss (dB) @25°C	≤1.1	≤0.8	≤0.8
3	VSWR (In BW)	≤1.6	≤1.5	≤1.5
4	Ripple	≤0.8	≤0.6	≤0.6
5	Impedance (Ω)	50	50	50
6	Attenuation (dB)	450~990MHz	≥50	-
		660~1440 MHz	-	≥50
		960~2034MHz	-	≥50
7	Power(W)	5W		
<b>Operating &amp; Storage Condition (Component)</b>				
Operation Temperature Range: -40°C ~ +85°C				
Storage Temperature Range: -40°C~ +85°C				
<b>Storage Condition before Soldering (Included packaging material)</b>				
Storage Temperature Range: +5 ~ +40 °C				
Humidity: 30 to 70% relative humidity				

### Construction

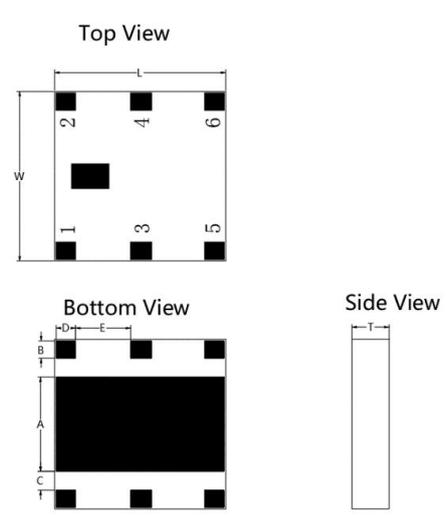


PIN	Connection	PIN	Connection
1	LPF1 input Port	2	LPF1 output Port
3	LPF2 input Port	4	LPF2 output Port

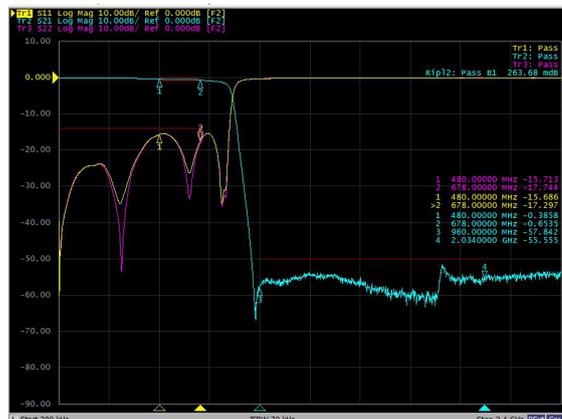
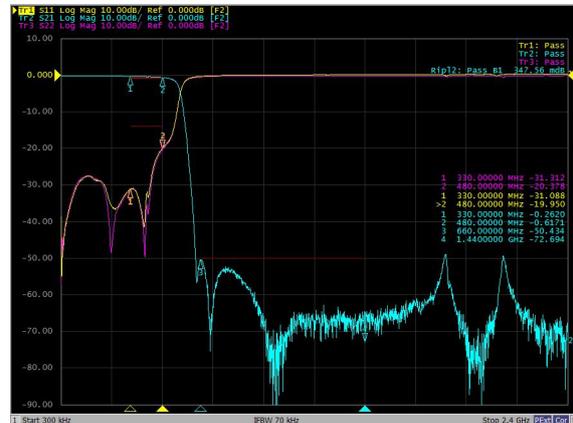
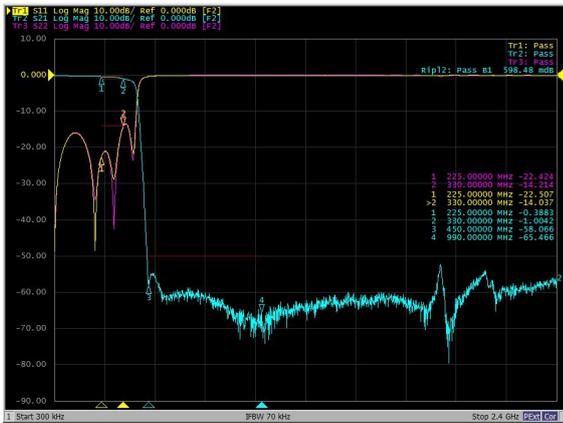
### Mounting Considerations



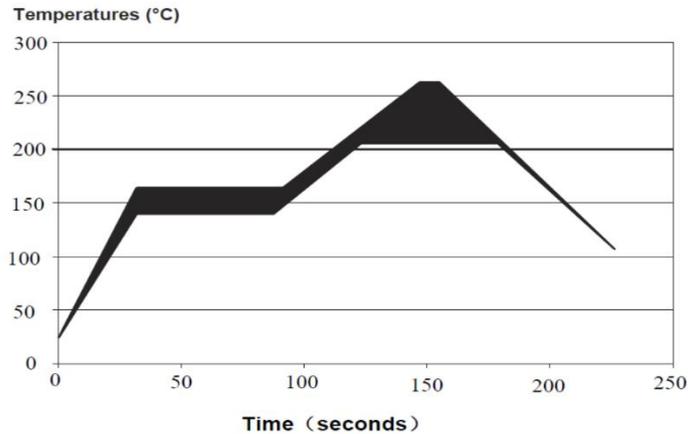
### Dimensions

Figure	Symbol	Dimension (mm)
	L	9.00 ± 0.20
	W	9.00 ± 0.20
	T	2.50 ± 0.20
	A	5.00 ± 0.15
	B	0.92 ± 0.15
	C	1.00 ± 0.15
	D	1.10 ± 0.15
E	2.90 ± 0.15	

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.